

USSN 10/068,159

PATENT RESPONSE

AMENDED SPECIFICATIONS

Please change the "Abstract" as follows:

Semiconductor devices and stacked die assemblies, and methods of fabricating the devices and assemblies for increasing semiconductor device density are provided, which have at least two semiconductor dies disposed on a substrate in a stacked arrangement, the first and second dies having first surfaces having bond pads, the second die having a second surface with a recessed edge portion along a perimeter of that die, and the recessed edge portion having a height sufficient for clearance of bonding elements extending from the first die.